

INTERCONNECTS

SERIES 850, 851, 852, 853 • .050" GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

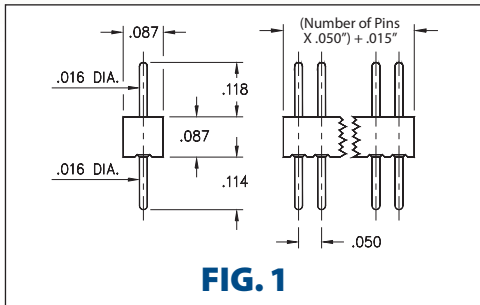


FIG. 1



FIG. 2



FIG. 3

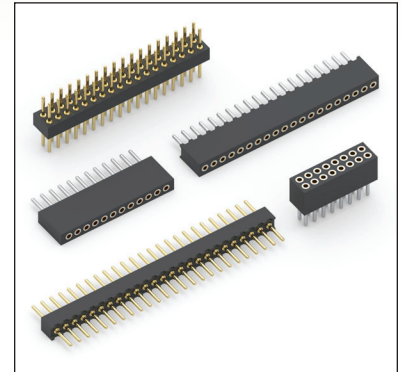


FIG. 4



FIG. 5

- Series 850, 851, 852, 853 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248"
- Pin headers have .016" dia. pins (MM #4006-0) See page 208 for details
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from .015"-.020"). See pages 158 and 160 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001	Single Row .087" Profile Pin Header					
		850-XX-0__-10-001000 Specify number of pins 01-50					
FIG. 2	Series 852...001	Double Row .083" Profile Pin Header					
		852-XX-__-10-001000 Specify number of pins 004-100					
							
SPECIFY PLATING CODE XX=		10 	90	40 			
Pin Plating 		10 μ" Au	200 μ" Sn/Pb	200 μ" Sn			
FIG. 3	Series 851...001	Single Row .161" Profile Socket					
		851-XX-0__-10-001000 Specify number of pins 01-50					
FIG. 4	Series 853...001	Double Row .161" Profile Socket					
		853-XX-__-10-001000 Specify number of pins 004-100					
FIG. 5	Series 851...002	Single Row .185" Profile Socket					
		851-XX-0__-10-002000 Specify number of pins 01-77					
							
SPECIFY PLATING CODE XX=		91	93	99	41 	43 	47 
Sleeve (Pin) 		200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn	200 μ" Sn	200 μ" Sn
Contact (Clip) 		10 μ" Au	30 μ" Au	100 μ" Sn/Pb	10 μ" Au	30 μ" Au	Au Flash

